

C2
wherein said plurality of solder balls are electrically connected through said leads to corresponding ones of said connection pads, respectively.--

Amend claim 8 as follows:

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--8. (amended) The mounting structure of a semiconductor device as claimed in claim 4,

wherein the gap between said insulating sheet and said wiring substrate is filled with resin and a gap between solder balls is free of resin.--

Amend claim 14 as follows:

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~~--14. (amended) The insulating sheet as claimed in~~
claim 13,

wherein said fixed one end of each of said leads includes a portion shaped to receive by direct contact, a corresponding one of a plurality of solder balls of a semiconductor chip, and said other end of each of said plurality of leads is shaped to contact with a corresponding one of a plurality of connection pads of a wiring substrate,

said portion being in contact with the first surface.--

CANCEL claim 17.

Add the following new claims:

--18. (new) A mounting structure of a semiconductor device, comprising:

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a semiconductor chip having a chip surface with a grid array of solder balls, the grid array being a first pattern;

a wiring substrate having a substrate surface with connection pads in a grid array of the first pattern,

the grid array of connection pads being out of vertical alignment with the grid array of the solder balls; and

an insulating sheet having a plurality of leads located intermediate the semiconductor chip and the wiring substrate,

the plurality of leads connecting ones of the solder balls with corresponding ones of the connection pads.

--19. (new) The structure of claim 18, wherein the grid array of the first pattern comprises at least three parallel rows of array positions.

--20. (new) The structure of claim 18, wherein,
the insulating sheet comprises holes;
the leads pass through the holes; and
the leads include a fixed portion in contact with the solder balls, the fixed portion also being in contact with a surface of the insulating sheet.

--21. (new) The structure of claim 19, wherein the insulating sheet comprises an elongate hole corresponding to each of the parallel rows.

--22. (new) The structure of claim 21, wherein, the leads pass through the holes; and

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C5* the leads include a fixed portion in contact with the solder balls, the fixed portion also being in contact with a surface of the insulating sheet.

--23. (new) The structure of claim 21, wherein, the elongate holes are filled with resin; and

a volume between the grid array of solder balls is free of resin.

--24. (new) The structure of claim 20, wherein, the elongate holes are filled with resin; and

a volume between the grid array of solder balls is free of resin.

--25. (new) The structure of claim 18, wherein at least some of the connection pads of the grid array of connection pads are located within a vertical extension of a perimeter of the semiconductor chip.--